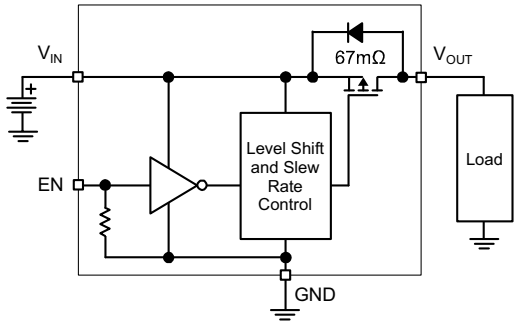
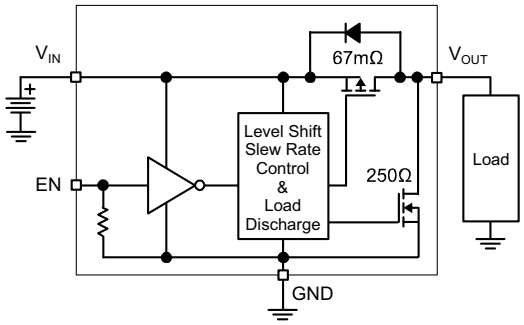
Typical Application Circuits

MIC94080 (Ultra-Fast Turn-On)
MIC94082 (800 µs Soft-Start)
MIC94084 (120 µs Soft-Start)



MIC94081 (Ultra-Fast Turn-On w/ Auto-Discharge)
MIC94083 (800 µs Soft-Start w/ Auto-Discharge)
MIC94085 (120 µs Soft-Start w/ Auto-Discharge)



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Voltage (V_{IN}) ..... +6V
Enable Voltage (V_{EN}) ..... +6V
Continuous Drain Current (I_D) (Note 1)
T_A = +25°C ..... ±2.0A
T_A = +85°C ..... ±1.5A
Pulsed Drain Current (I_{DP}) (Note 2) ..... ±6.0A
Continuous Diode Current (I_S) (Note 3) ..... –50 mA
Storage Temperature (T_S) ..... –55°C to +150°C
ESD Rating (HBM, Note 4) ..... 3 kV

Operating Ratings ††

Input Voltage (V_{IN}) ..... +1.7V to +5.5V
Junction Temperature Range (T_J) ..... –40°C to +125°C
Package Thermal Resistance
4-Ld FTDFN 0.85 mm x 0.85 mm (θ_{JA}) ..... 140°C/W
4-Ld FTDFN 0.85 mm x 0.85 mm (θ_{JC}) ..... 85°C/W

† Notice: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

†† Notice: The device is not guaranteed to function outside its operating ratings.

Note 1: With thermal contact to PCB. See Thermal Considerations section.

2: Pulse width <300 µs with <2% duty cycle.

3: Continuous body diode current conduction (reverse conduction, i.e. V_{OUT} to V_{IN}) is not recommended.

4: Devices are ESD sensitive. Handling precautions recommended. Human body model, 1.5 kΩ in series with 100 pF.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: T_A = +25°C, **bold** values indicate –40°C ≤ T_A ≤ +85°C, unless noted.

Parameter	Sym.	Min.	Typ.	Max.	Units	Conditions
Enable Threshold Voltage	V_{EN_TH}	**0.4**	—	**1.25**	V	V_{IN} = 1.7V to 4.5V, I_D = –250 µA
Quiescent Current	I_Q	—	0.1	**1**	µA	V_{IN} = V_{EN} = 5.5V, I_D = OPEN Measured on V_{IN} MIC94080/1
		—	8	**15**		V_{IN} = V_{EN} = 5.5V, I_D = OPEN Measured on V_{IN} MIC94082/3/4/5
Enable Input Current	I_{EN}	—	2.8	**4**	µA	V_{IN} = V_{EN} = 5.5V, I_D = OPEN
Quiescent Current (Shutdown)	I_{SHUT-Q}	—	0.02	**1**	µA	V_{IN} = +5.5V, V_{EN} = 0V, I_D = OPEN Measured on V_{IN}, Note 1
OFF State Leakage Current	$I_{SHUT-SWITCH}$	—	0.02	**1**	µA	V_{IN} = +5.5V, V_{EN} = 0V, I_D = SHORT Measured on V_{IN}, Note 1
P-Channel Drain-to-Source ON Resistance	$R_{DS(ON)}$	—	67	**115**	mΩ	V_{IN} = +5.0V, I_D = –100 mA, V_{EN} = 1.5V
		—	70	**130**		V_{IN} = +4.5V, I_D = –100 mA, V_{EN} = 1.5V
		—	80	**165**		V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V
		—	110	**225**		V_{IN} = +2.5V, I_D = –100 mA, V_{EN} = 1.5V
		—	175	**350**		V_{IN} = +1.8V, I_D = –100 mA, V_{EN} = 1.5V
		—	200	**375**		V_{IN} = +1.7V, I_D = –100 mA, V_{EN} = 1.5V
Turn-Off Resistance	$R_{SHUTDOWN}$	—	250	**400**	Ω	V_{IN} = +3.6V, I_{TEST} = 1 mA, V_{EN} = 0V MIC94081/3/5
Dynamic Electrical Characteristics						
Turn-On Delay	t_{ON_DLY}	—	0.4	1.5	µs	V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V MIC94080, MIC94081
		200	600	1500		V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V MIC94082, MIC94083
		65	110	165		V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V MIC94084, MIC94085
Turn-On Rise Time	t_{ON_RISE}	—	0.4	1.5	µs	V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V MIC94080, MIC94081
		400	800	1500		V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V MIC94082, MIC94083
		65	120	175		V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 1.5V MIC94084, MIC94085
Turn-Off Delay Time	t_{OFF_DLY}	—	60	200	ns	V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 0V
Turn-Off Fall Time	t_{OFF_FALL}	—	20	100	ns	V_{IN} = +3.6V, I_D = –100 mA, V_{EN} = 0V

Note 1: Measured on the MIC94080YFT.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Junction Temperature Range	T_J	–40	—	+125	°C	—
Storage Temperature Range	T_S	–55	—	+150	°C	—
Package Thermal Resistances						
Thermal Resistance, 4-Ld FTDFN 0.85 mm x 0.85 mm	θ_{JA}	—	140	—	°C/W	—
Thermal Resistance, 4-Ld FTDFN 0.85 mm x 0.85 mm	θ_{JC}	—	85	—	°C/W	—

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

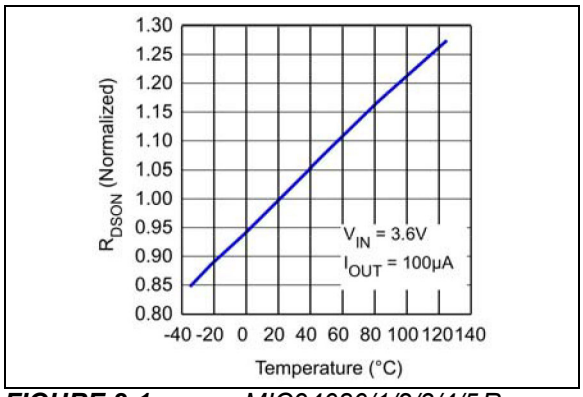


FIGURE 2-1: *MIC94080/1/2/3/4/5 $R_{DS(ON)}$ Variance vs. Temperature.*

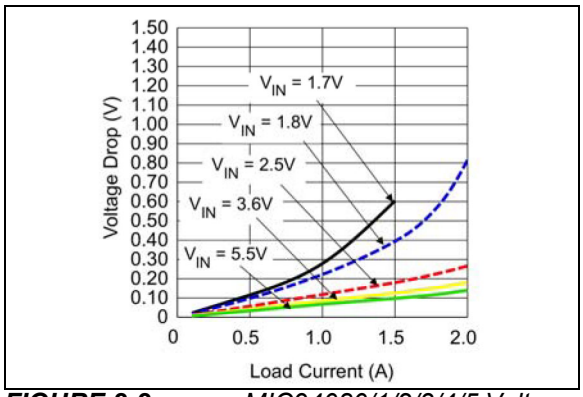


FIGURE 2-2: *MIC94080/1/2/3/4/5 Voltage Drop vs. Load Current.*

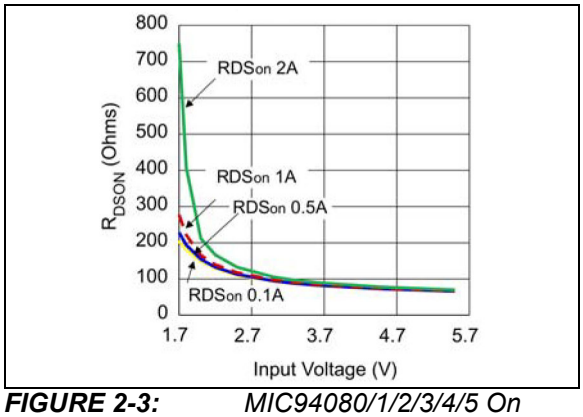


FIGURE 2-3: *MIC94080/1/2/3/4/5 On Resistance vs. Input Voltage.*

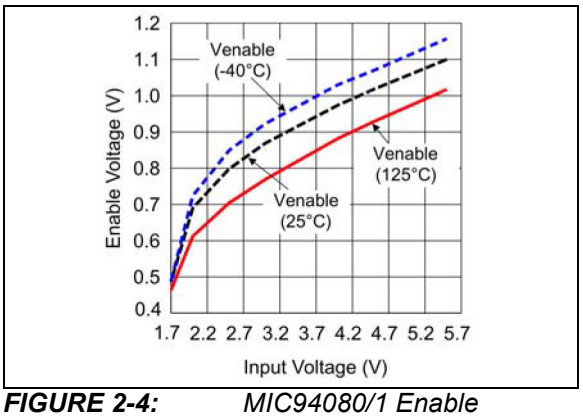


FIGURE 2-4: *MIC94080/1 Enable Threshold vs. Input Voltage.*

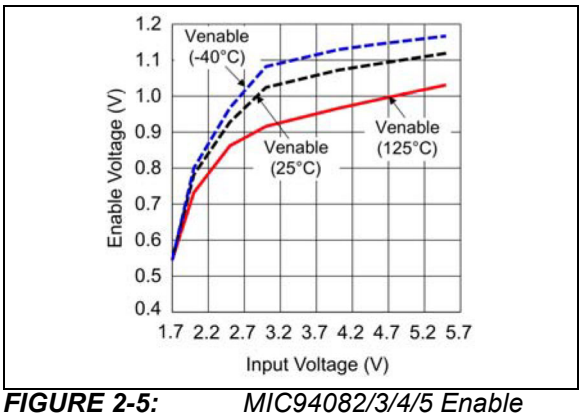


FIGURE 2-5: *MIC94082/3/4/5 Enable Threshold vs. Input Voltage.*

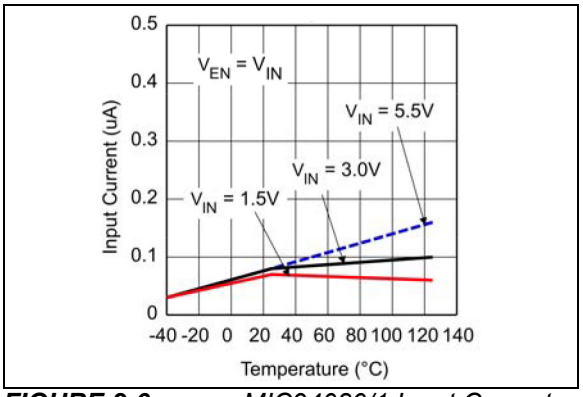


FIGURE 2-6: *MIC94080/1 Input Current vs. Temperature.*

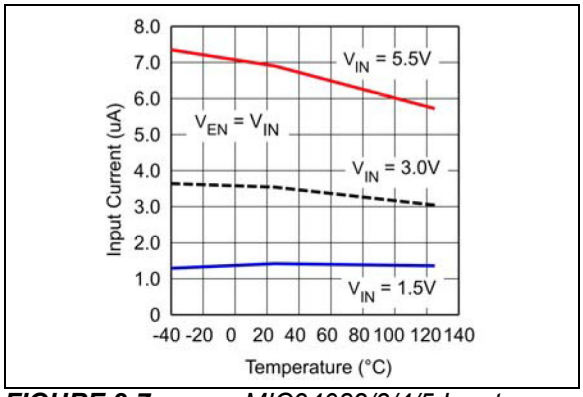


FIGURE 2-7: *MIC94082/3/4/5 Input Current vs. Temperature.*

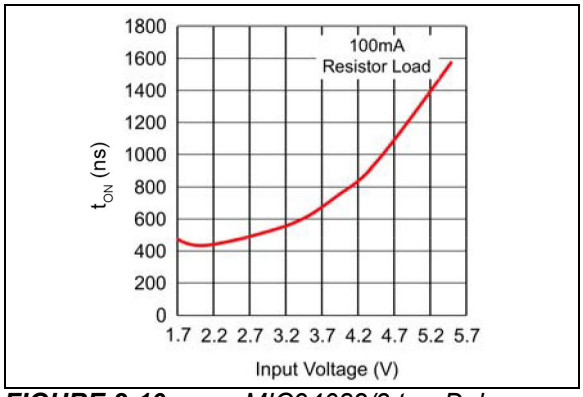


FIGURE 2-10: *MIC94082/3 t_{ON} Delay vs. Input Voltage.*

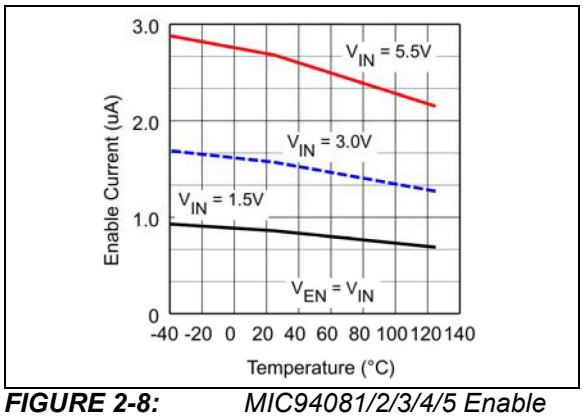


FIGURE 2-8: *MIC94081/2/3/4/5 Enable Current vs. Temperature.*

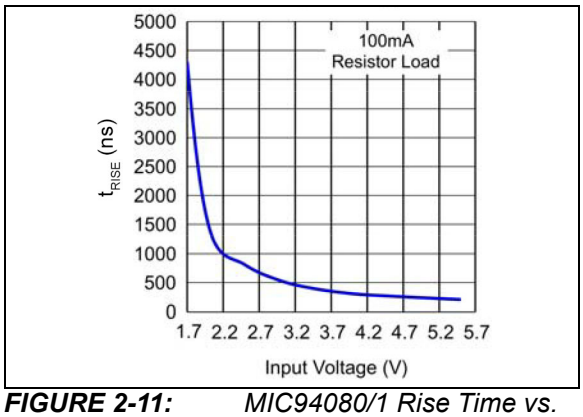


FIGURE 2-11: *MIC94080/1 Rise Time vs. Input Voltage.*

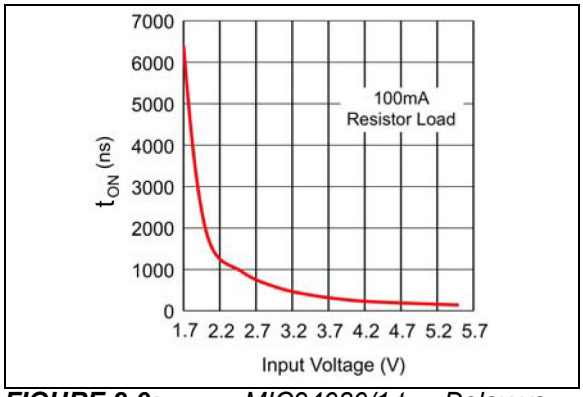


FIGURE 2-9: *MIC94080/1 t_{ON} Delay vs. Input Voltage.*

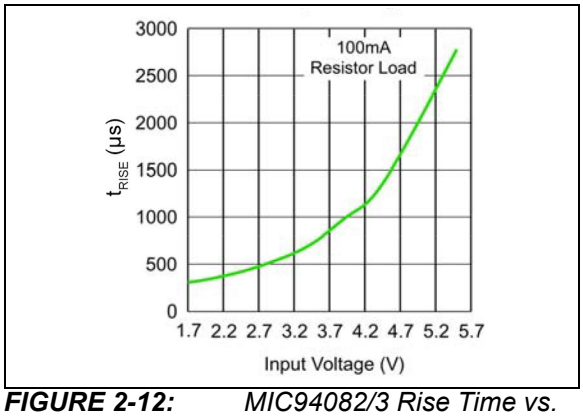


FIGURE 2-12: *MIC94082/3 Rise Time vs. Input Voltage.*

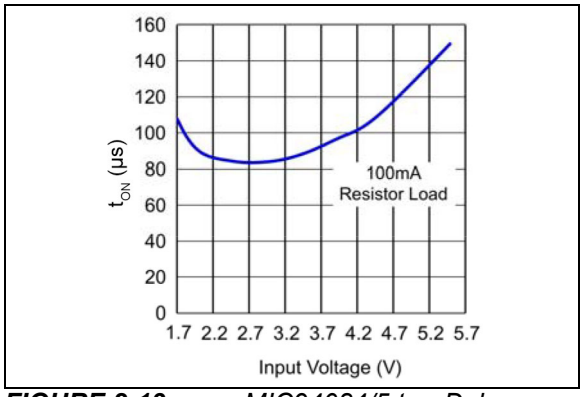


FIGURE 2-13: *MIC94084/5 t_{ON} Delay vs. Input Voltage.*

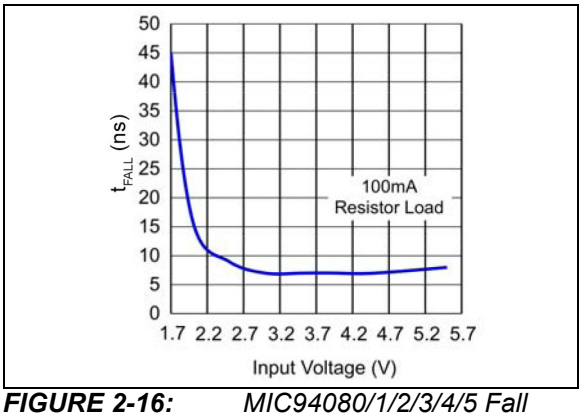


FIGURE 2-16: *MIC94080/1/2/3/4/5 Fall Time vs. Input Voltage.*

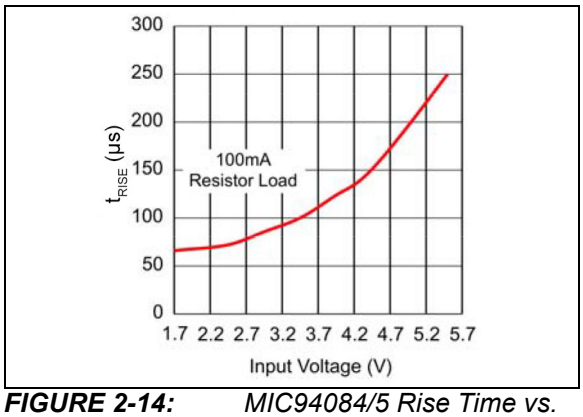


FIGURE 2-14: *MIC94084/5 Rise Time vs. Input Voltage.*

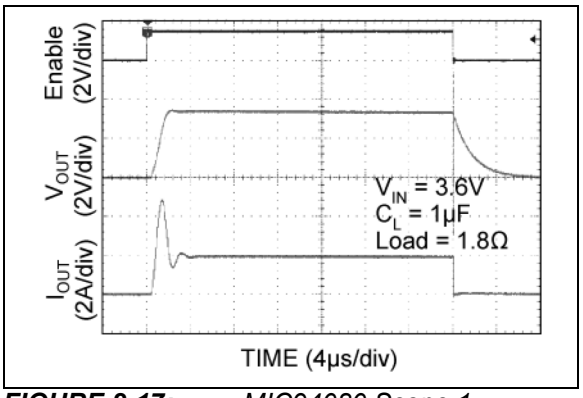


FIGURE 2-17: *MIC94080 Scope 1.*

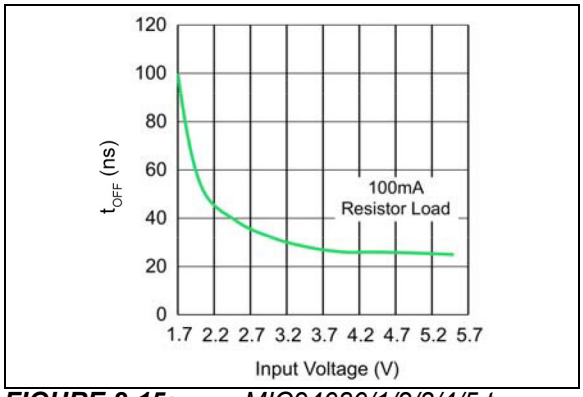


FIGURE 2-15: *MIC94080/1/2/3/4/5 t_{OFF} Delay vs. Input Voltage.*

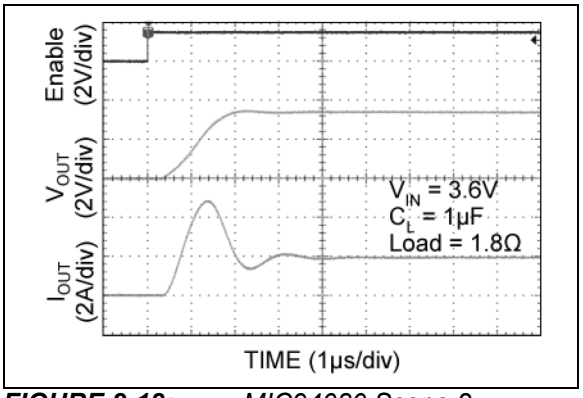


FIGURE 2-18: *MIC94080 Scope 2.*

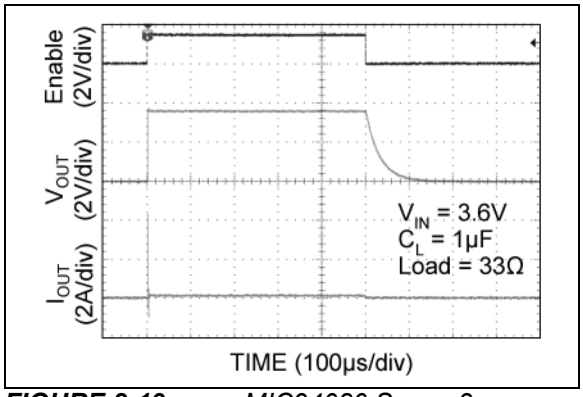


FIGURE 2-19: *MIC94080 Scope 3.*

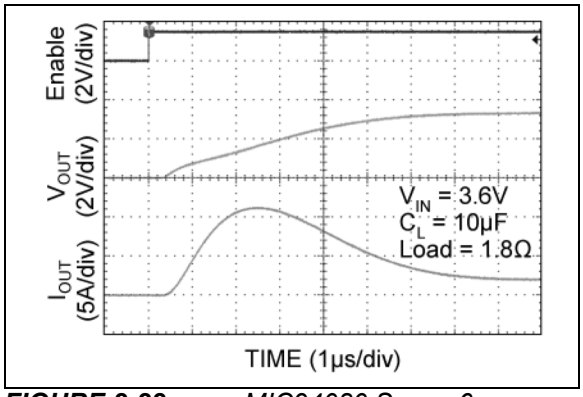


FIGURE 2-22: *MIC94080 Scope 6.*

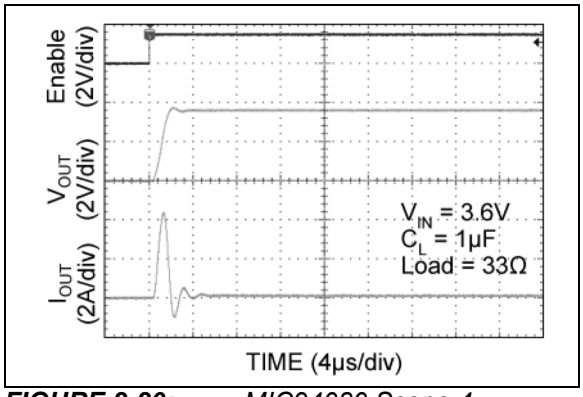


FIGURE 2-20: *MIC94080 Scope 4.*

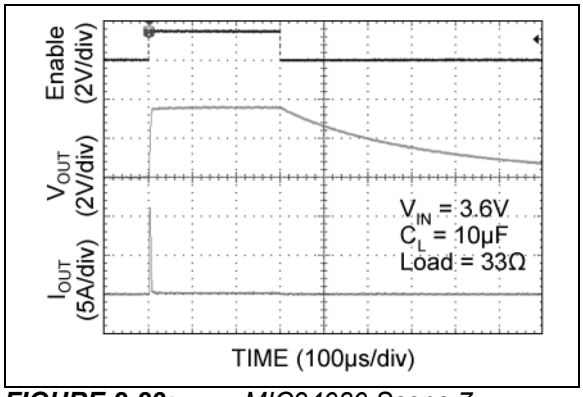


FIGURE 2-23: *MIC94080 Scope 7.*

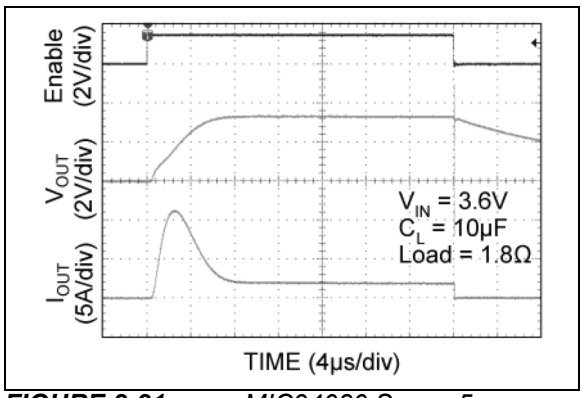


FIGURE 2-21: *MIC94080 Scope 5.*

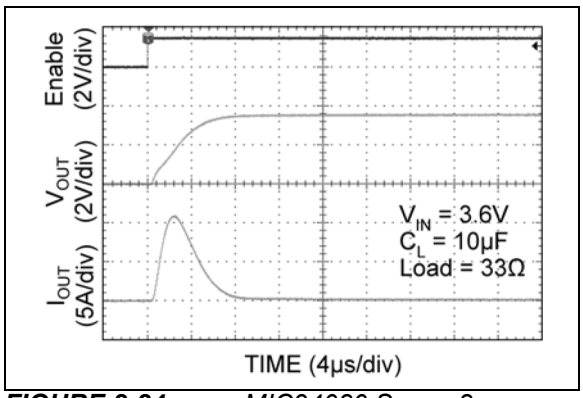


FIGURE 2-24: *MIC94080 Scope 8.*

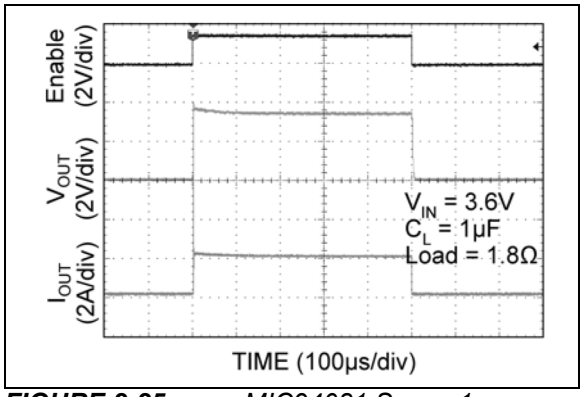


FIGURE 2-25: *MIC94081 Scope 1.*

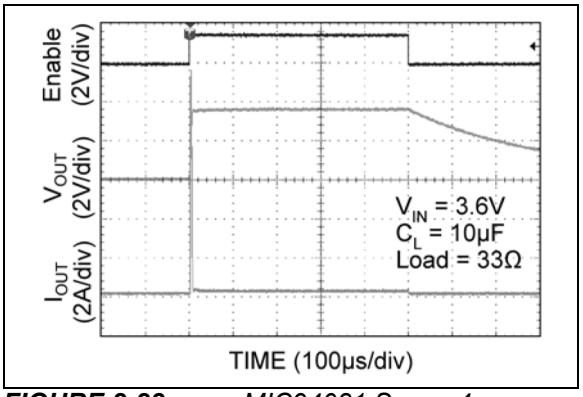


FIGURE 2-28: *MIC94081 Scope 4.*

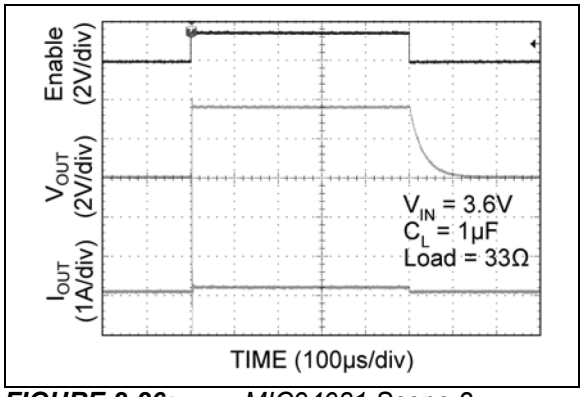


FIGURE 2-26: *MIC94081 Scope 2.*

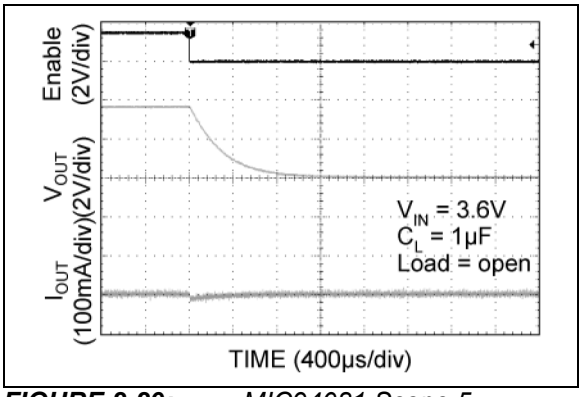


FIGURE 2-29: *MIC94081 Scope 5.*

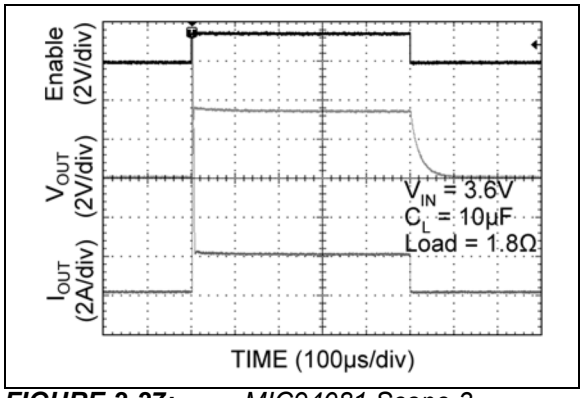


FIGURE 2-27: *MIC94081 Scope 3.*

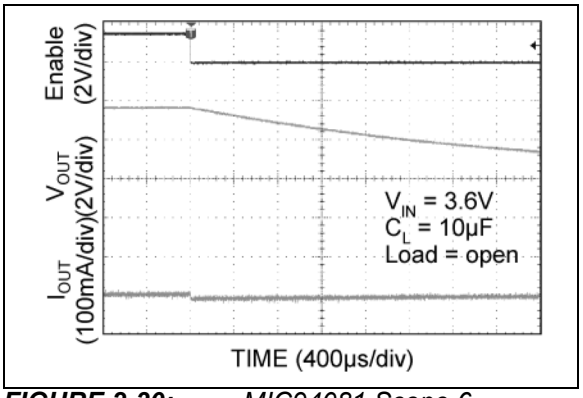


FIGURE 2-30: *MIC94081 Scope 6.*

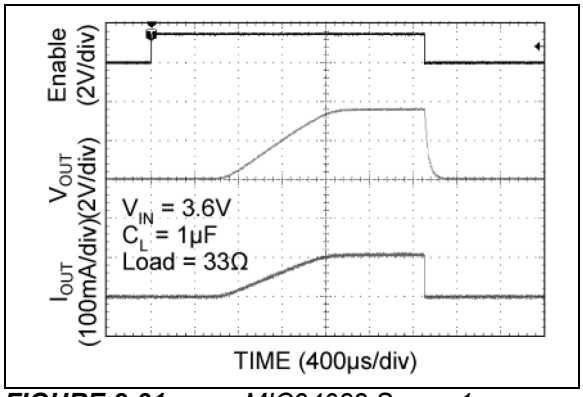


FIGURE 2-31: *MIC94082 Scope 1.*

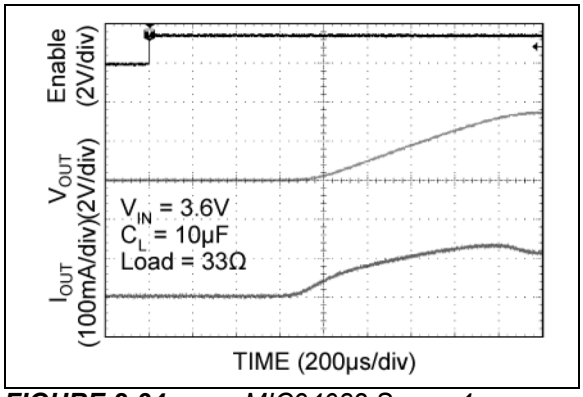


FIGURE 2-34: *MIC94082 Scope 4.*

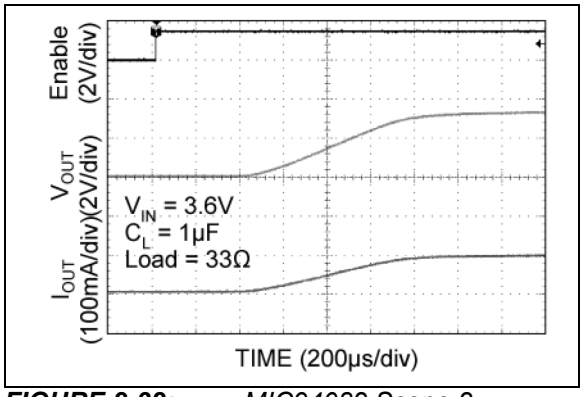


FIGURE 2-32: *MIC94082 Scope 2.*

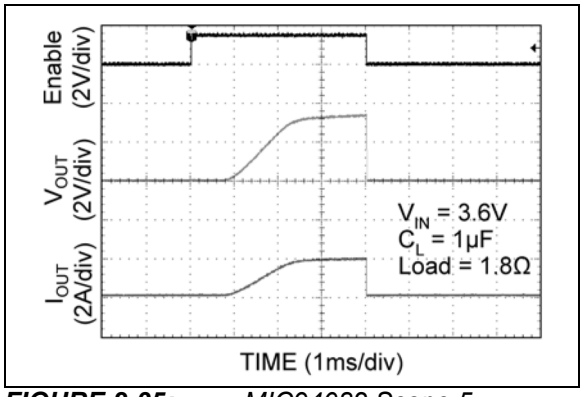


FIGURE 2-35: *MIC94082 Scope 5.*

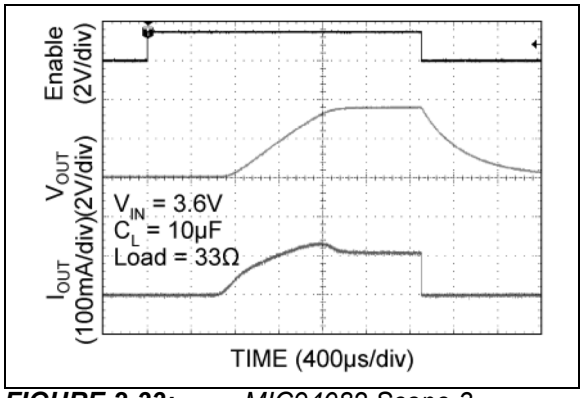


FIGURE 2-33: *MIC94082 Scope 3.*

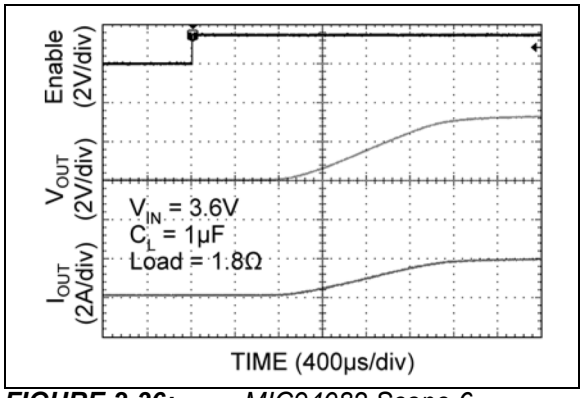


FIGURE 2-36: *MIC94082 Scope 6.*

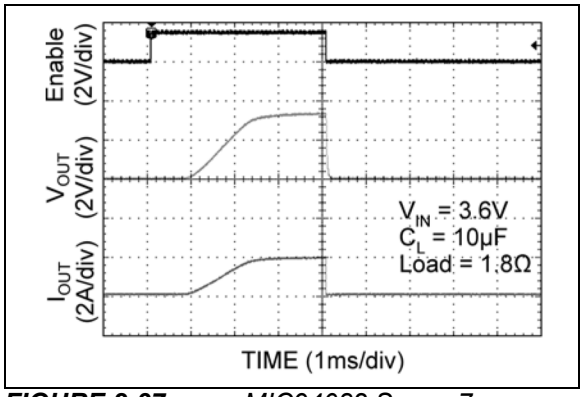


FIGURE 2-37: *MIC94082 Scope 7.*

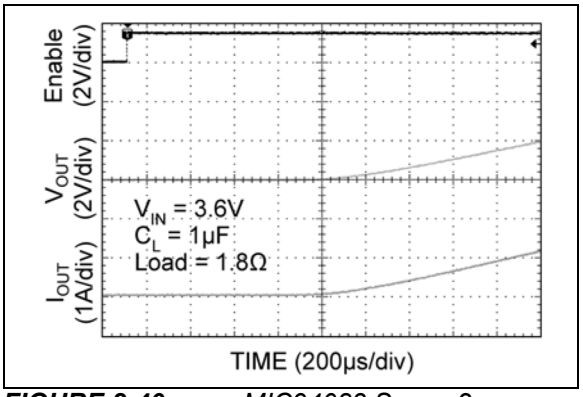


FIGURE 2-40: *MIC94083 Scope 2.*

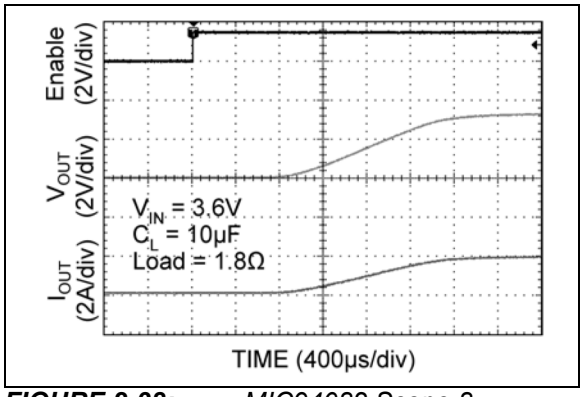


FIGURE 2-38: *MIC94082 Scope 8.*

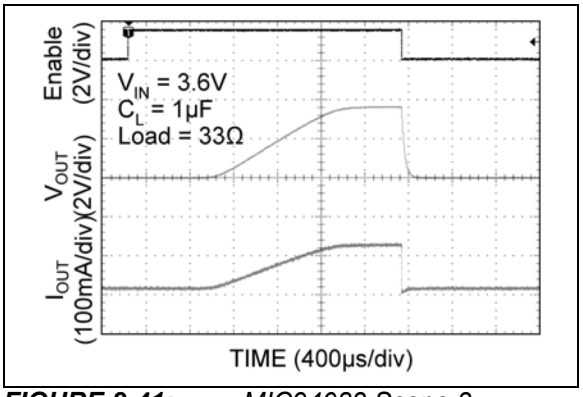


FIGURE 2-41: *MIC94083 Scope 3.*

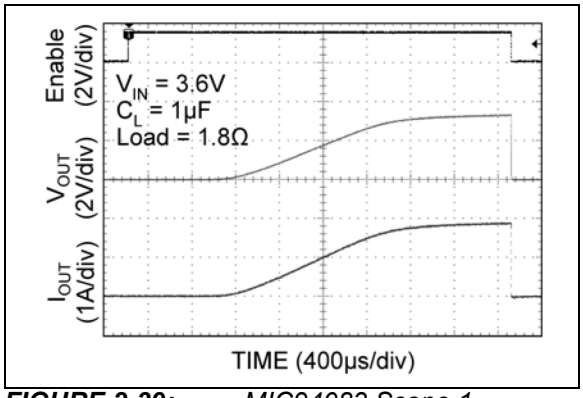


FIGURE 2-39: *MIC94083 Scope 1.*

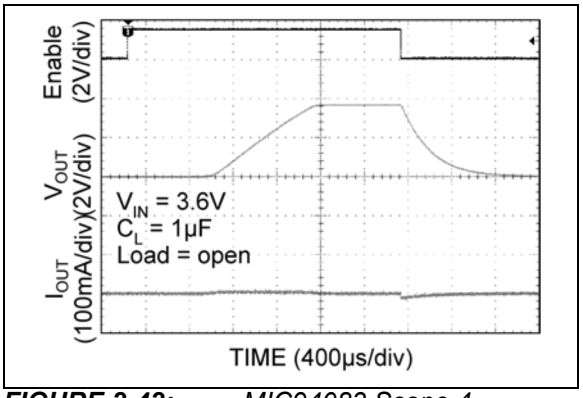


FIGURE 2-42: *MIC94083 Scope 4.*

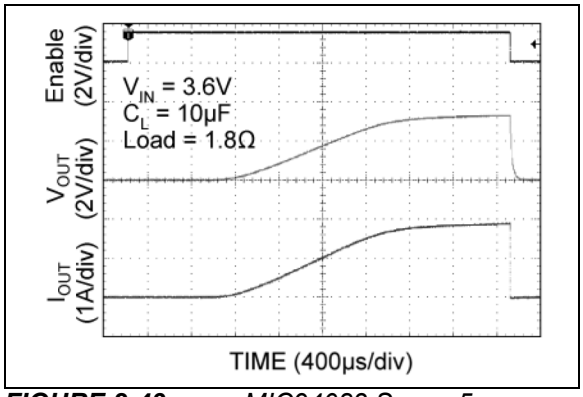


FIGURE 2-43: *MIC94083 Scope 5.*

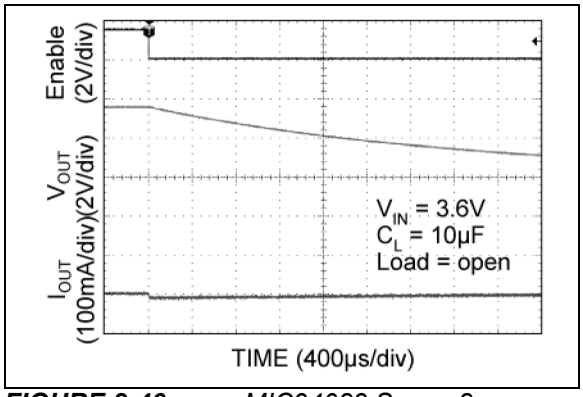


FIGURE 2-46: *MIC94083 Scope 8.*

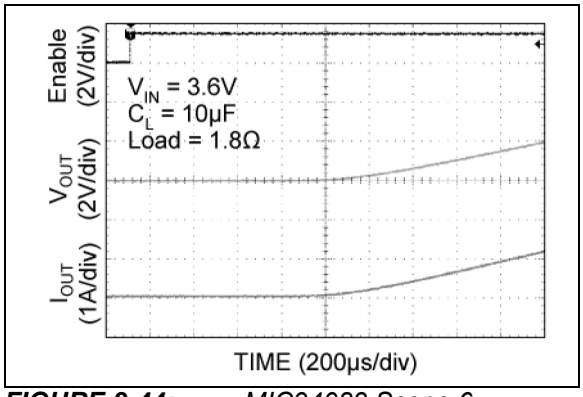


FIGURE 2-44: *MIC94083 Scope 6.*

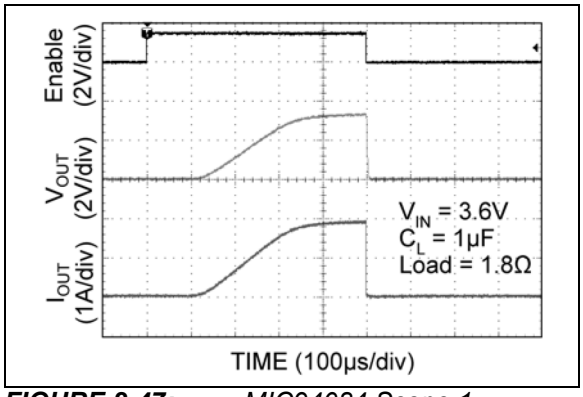


FIGURE 2-47: *MIC94084 Scope 1.*

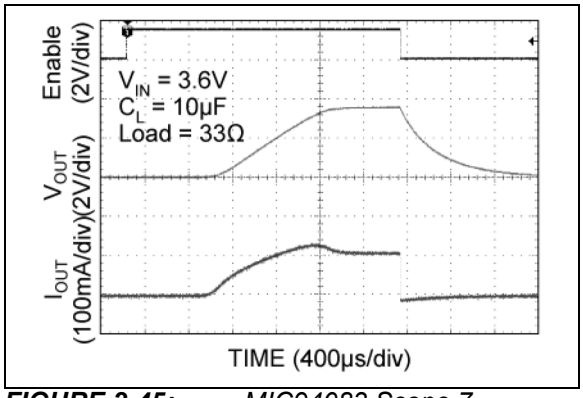


FIGURE 2-45: *MIC94083 Scope 7.*

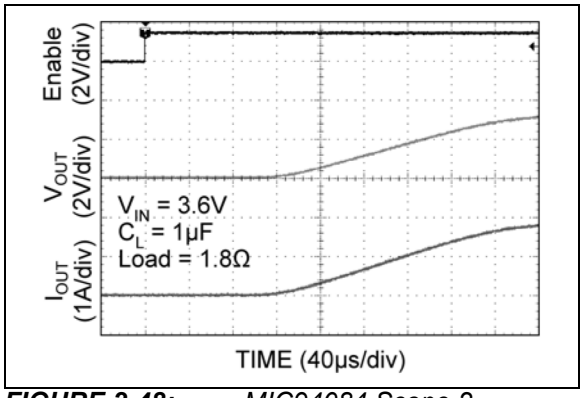


FIGURE 2-48: *MIC94084 Scope 2.*

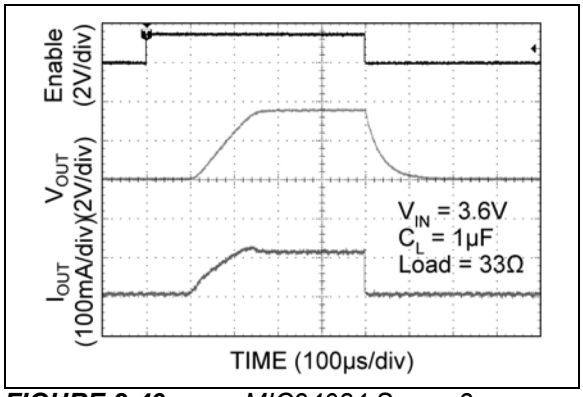


FIGURE 2-49: *MIC94084 Scope 3.*

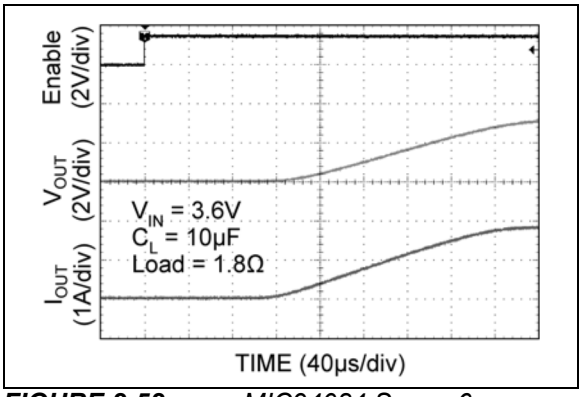


FIGURE 2-52: *MIC94084 Scope 6.*

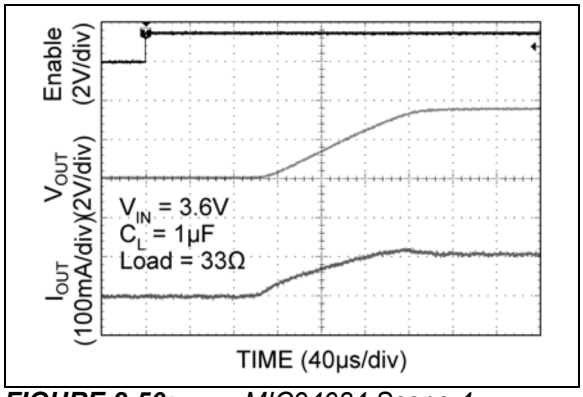


FIGURE 2-50: *MIC94084 Scope 4.*

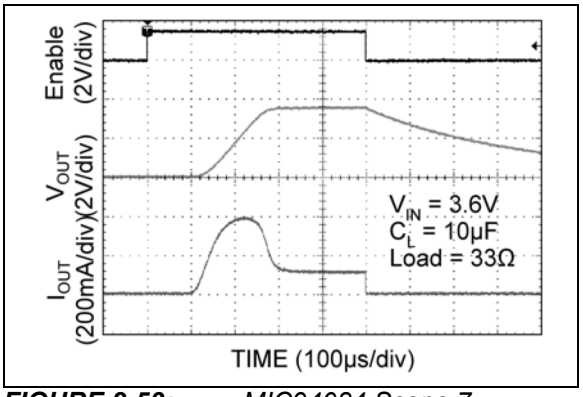


FIGURE 2-53: *MIC94084 Scope 7.*

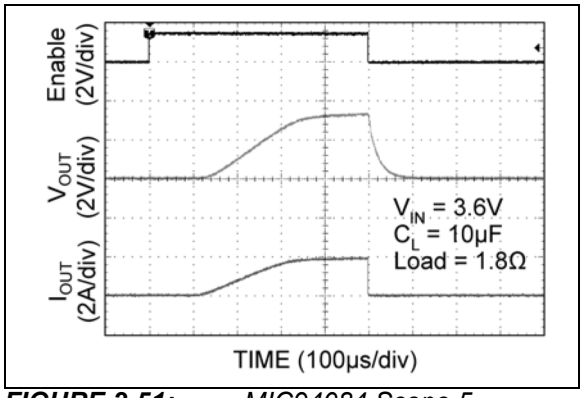


FIGURE 2-51: *MIC94084 Scope 5.*

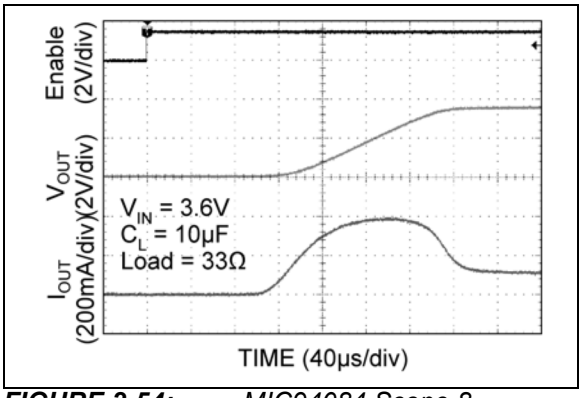


FIGURE 2-54: *MIC94084 Scope 8.*

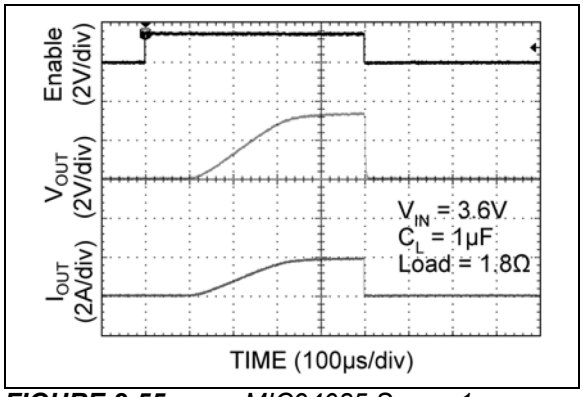


FIGURE 2-55: *MIC94085 Scope 1.*

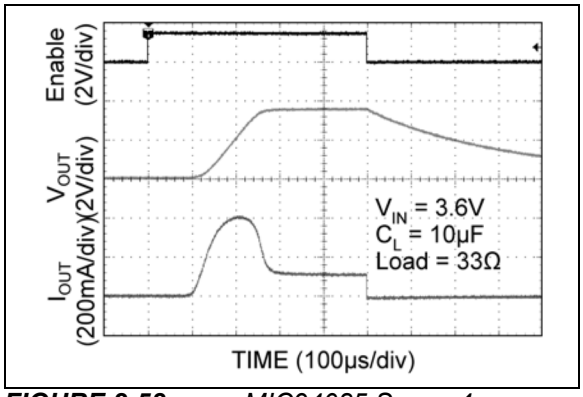


FIGURE 2-58: *MIC94085 Scope 4.*

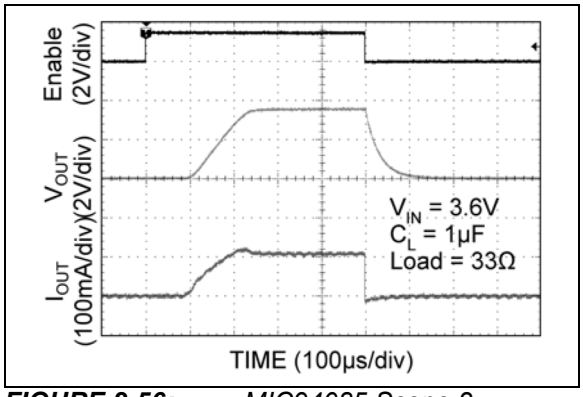


FIGURE 2-56: *MIC94085 Scope 2.*

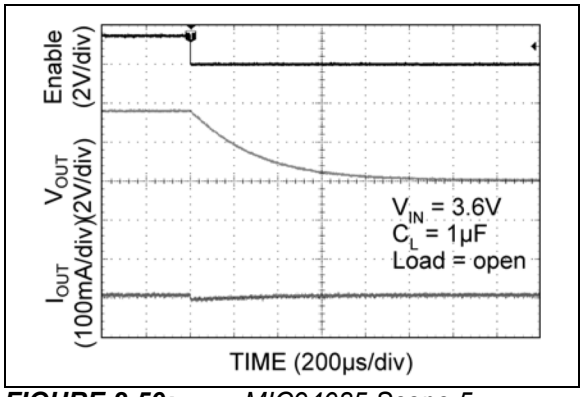


FIGURE 2-59: *MIC94085 Scope 5.*

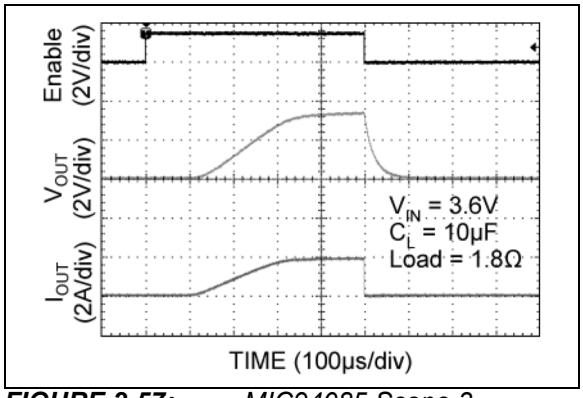


FIGURE 2-57: *MIC94085 Scope 3.*

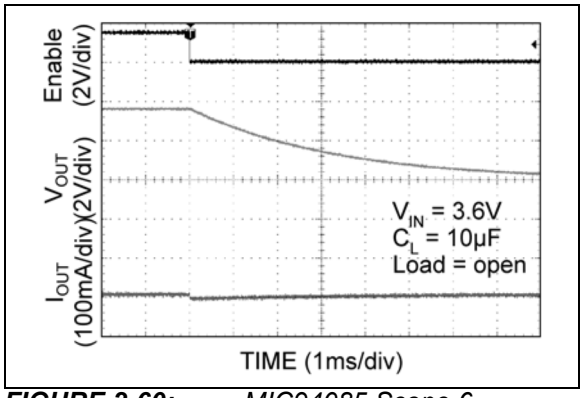


FIGURE 2-60: *MIC94085 Scope 6.*

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	V_{OUT}	Drain of P-Channel MOSFET.
2	GND	Ground. Should be connected to electrical ground.
3	V_{IN}	Source of P-Channel MOSFET.
4	EN	Enable (Input): Active-high CMOS/TTL control input for switch. Internal ~2 MΩ pull-down resistor. Output will be off if this pin is left floating.

4.0 APPLICATION INFORMATION

4.1 Power Switch SOA

The safe operating area (SOA) curve represents the boundary of maximum safe operating current and maximum safe operating junction temperature.

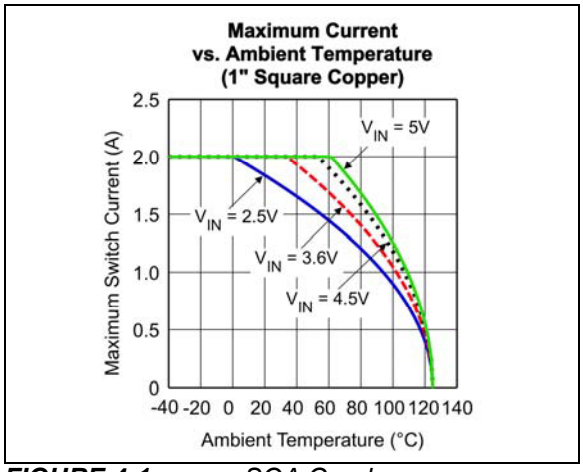


FIGURE 4-1: *SOA Graph.*

The curves above show the SOA for various V_{IN} values mounted on a typical one-layer, 1 square inch copper board.

4.2 Power Dissipation Considerations

As with all power switches, the current rating of the switch is limited mostly by the thermal properties of the package and the PCB on which it's mounted. There is a simple Ohm's law type relationship between thermal resistance, power dissipation, and temperature that are analogous to an electrical circuit.

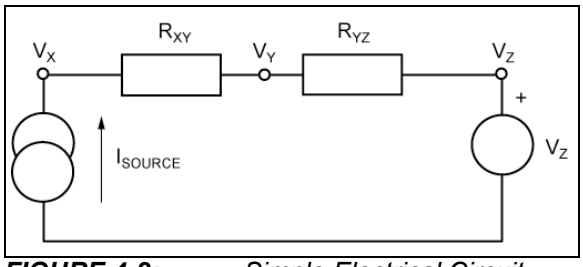


FIGURE 4-2: *Simple Electrical Circuit.*

From this simple circuit, one can calculate V_X if one knows I_{SOURCE}, V_Z, and the resistor values for R_{XY} and R_{YZ} using Equation 4-1.

EQUATION 4-1:

$$V_X = I_{SOURCE} \times (R_{XY} + R_{YZ}) + V_Z$$

Thermal circuits can be considered using these same rules and can be drawn similarly by replacing current sources with power dissipation (in Watts), resistance with thermal resistance (in °C/W), and voltage sources with temperature (in °C).

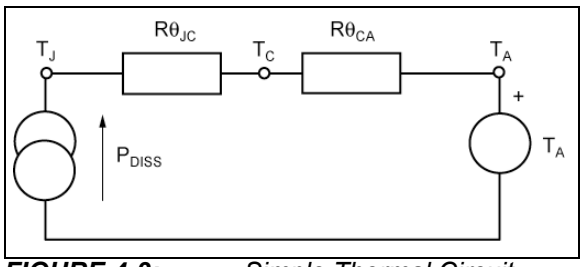


FIGURE 4-3: *Simple Thermal Circuit.*

By replacing the variables in the equation for V_X, one can find the junction temperature (T_J) from power dissipation, ambient temperature, and then know thermal resistance of the PCB ($R\theta_{CA}$) and the package ($R\theta_{JC}$).

EQUATION 4-2:

$$T_J = P_{DISS} \times (R\theta_{JC} + R\theta_{CA}) + T_A$$

P_{DISS} is calculated as I_{SWITCH}^2 x $R_{SW(MAX)}$. $R\theta_{JC}$ is found in the Temperature Specifications section of this data sheet and $R\theta_{CA}$ (the PCB thermal resistance) values for various PCB copper areas is discussed in Designing with Low Dropout Voltage Regulators.

4.2.1 AN EXAMPLE

A switch is intended to drive a 1A load and is placed on a PCB that has a ground plane area of at least 25 mm by 25 mm (625 mm^2). The voltage source is a Li-ion battery with a lower operating threshold of 3V and the ambient temperature of the assembly can be up to 50°C.

Summary of variables:

- I_{SW} = 1A
- V_{IN} = 3V to 4.2V
- T_A = 50°C
- $R\theta_{JC}$ = 85°C/W
- $R\theta_{CA}$ = 53°C/W (as read from Figure 4-4)

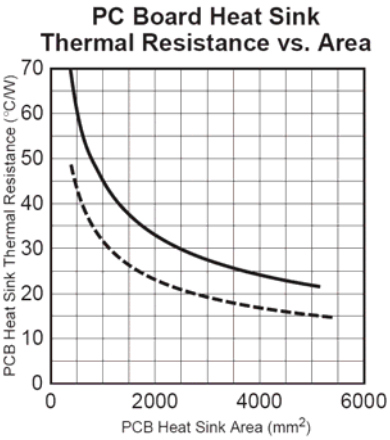


FIGURE 4-4: *Excerpt from the LDO Book.*

EQUATION 4-3:

$$P_{DISS} = I_{SW}^{2} \times R_{SW(MAX)}$$

The worst case switch resistance ($R_{SW(MAX)}$) at the lowest V_{IN} of 3V is not available in the data sheet, so the next lowest value of V_{IN} is used.

$R_{SW(MAX)}$ at 2.5V is 200 mΩ.

An additional consideration is to allow for the maximum junction temperature of 125°C. If this was a calculation for the worst case $R_{SW(MAX)}$ for 25°C, the actual worst case resistance in this case can be 30% higher (see Figure 2-1). However, 200 mΩ is the maximum over temperature. Therefore:

EQUATION 4-4:

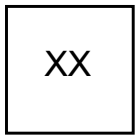
$$T_J = 1^2 \times 0.2 \times (85 + 53) + 50 = 78°C$$

This is below the maximum of 125°C.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

4-Lead FTDFN*



Example

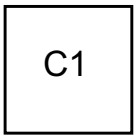


TABLE 5-1: MARKING CODES

Part Number	Marking Code	Features
MIC94080YFT-TR	C1	Fast Turn-On
MIC94081YFT-TR	C2	Fast Turn-On, Load Discharge
MIC94082YFT-TR	C5	800 µs Soft-Start
MIC94083YFT-TR	C7	800 µs Soft-Start, Load Discharge
MIC94084YFT-TR	C0	120 µs Soft-Start
MIC94085YFT-TR	1C	120 µs Soft-Start, Load Discharge

Legend:	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	●, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).

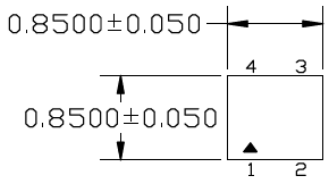
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

Underbar (_) and/or Overbar (¯) symbol may not be to scale.

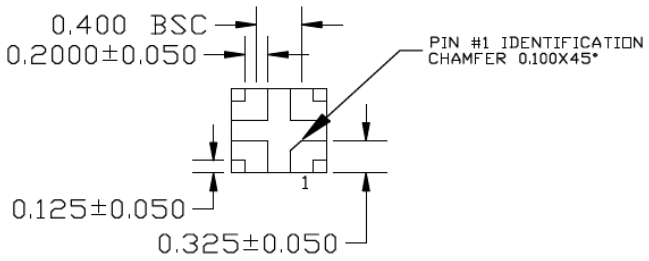
4-Lead FTDFN Package Outline & Recommended Land Pattern

TITLE
4 LEAD FTDFN 0.85x0.85 mm PACKAGE (Flip Chip) OUTLINE & RECOMMENDED LAND PATTERN

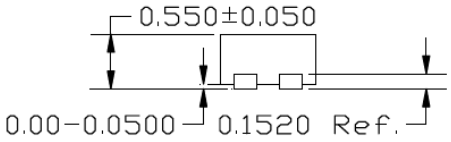
DRAWING #	FTDFN085085-4LD-PL-1	**UNIT**	MM
LEAD FRAME	Copper Alloy	**LEAD FINISH**	NiPdAu



TOP VIEW
NOTE: 1, 2, 3



BOTTOM VIEW
NOTE: 1, 2, 3



END VIEW
NOTE: 1, 2, 3

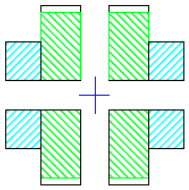
NOTE:
1. MAX PACKAGE WARPAGE IS 0.05 MM
2. MAX ALLOWABLE BURR IS 0.076 MM IN ALL DIRECTIONS
3. PIN #1 IS ON TOP WILL BE LASER MARKED
4. GREEN COLORED RECTANGLES (SHADED AREA) REPRESENT SOLDER STENCIL OPENING ON EXPOSED METAL TRACE.
5. CYAN COLORED RECTANGLES (SHADED AREA) REPRESENT OPTIONAL SOLDER STENCIL OPENING.

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

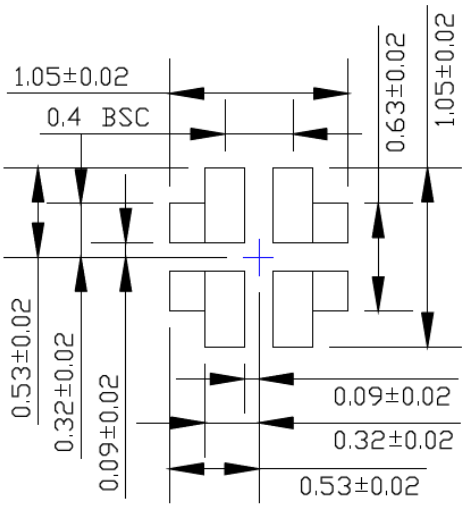
POD-Land Pattern drawing #FTDFN085085-4LD-PL-1

RECOMMENDED LAND PATTERN

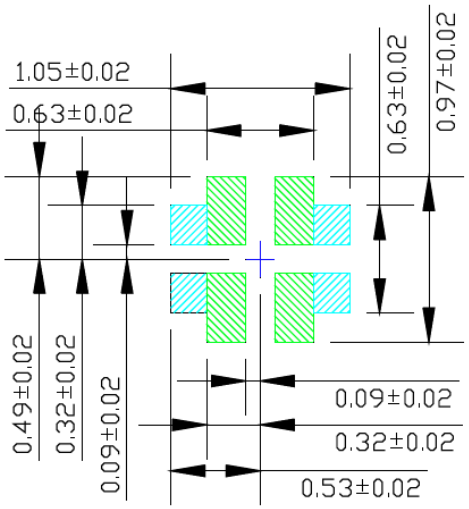
NOTE: 4, 5



STACKED-UP



EXPOSED METAL TRACE



SOLDER STENCIL OPENING

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging.

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (March 2019)

- Converted Micrel document MIC94080/1/2/3/4/5 to Microchip data sheet template DS20006118A.
- Minor grammatical text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

Device	X	XX	-XX
Part No.	Junction Temp. Range	Package	Media Type

Device:	MIC94080:	67 mΩ $R_{DS(ON)}$ 2A High-Side Load Switch with Fast Turn-On
	MIC94081:	67 mΩ $R_{DS(ON)}$ 2A High-Side Load Switch with Fast Turn-On and Load Discharge
	MIC94082:	67 mΩ $R_{DS(ON)}$ 2A High-Side Load Switch with 800 µs Soft-Start
	MIC94083:	67 mΩ $R_{DS(ON)}$ 2A High-Side Load Switch with 800 µs Soft-Start and Load Discharge
	MIC94084:	67 mΩ $R_{DS(ON)}$ 2A High-Side Load Switch with 120 µs Soft-Start
	MIC94085:	67 mΩ $R_{DS(ON)}$ 2A High-Side Load Switch with 120 µs Soft-Start and Load Discharge
Junction Temperature Range:	Y =	–40°C to +125°C, RoHS-Compliant
Package:	FT =	4-Lead 0.85 mm x 0.85 mm FTDFN
Media Type:	TR =	5,000/Reel

Examples:

a) MIC94080YFT-TR: MIC94080, –40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel

b) MIC94081YFT-TR: MIC94081, –40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel

c) MIC94082YFT-TR: MIC94082, –40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel

d) MIC94083YFT-TR: MIC94083, –40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel

e) MIC94084YFT-TR: MIC94084, –40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel

f) MIC94085YFT-TR: MIC94085, –40°C to +125°C Temperature Range, 4-Lead FTDFN, 5,000/Reel

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

NOTES:

Note the following details of the code protection feature on Microchip devices:

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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Fax: 34-91-708-08-91

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UK - Wokingham
Tel: 44-118-921-5800
Fax: 44-118-921-5820